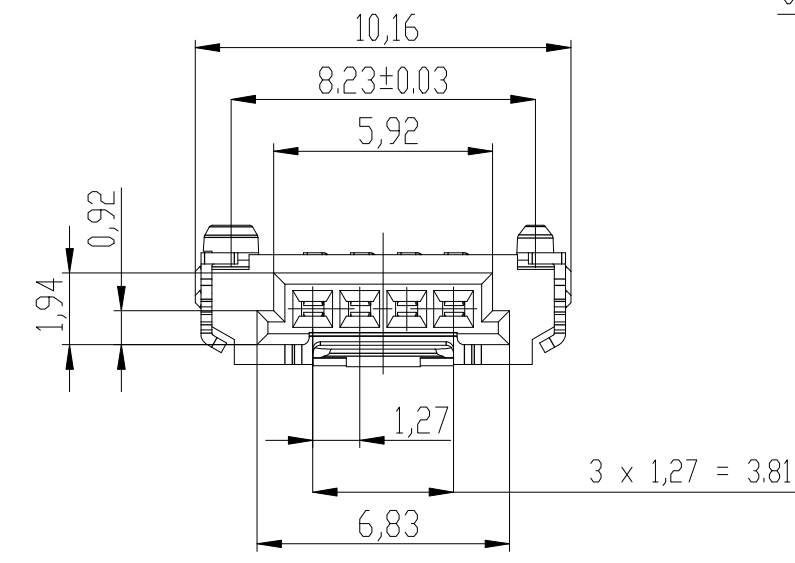
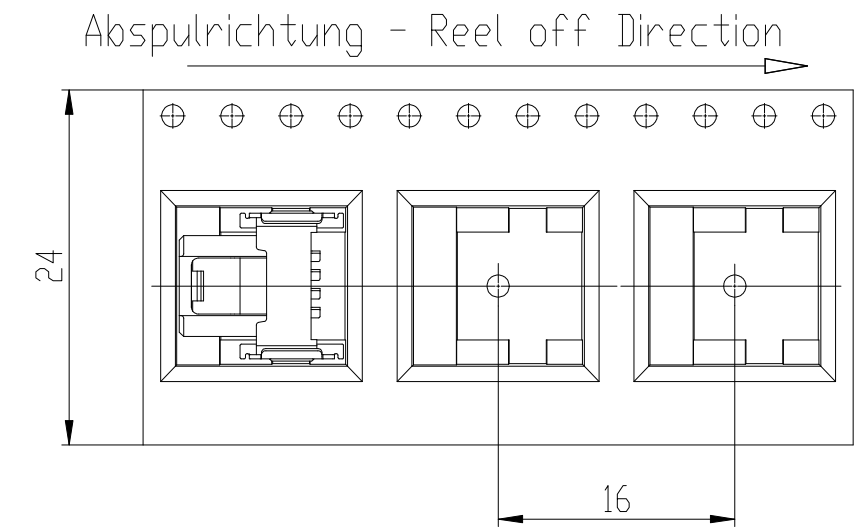
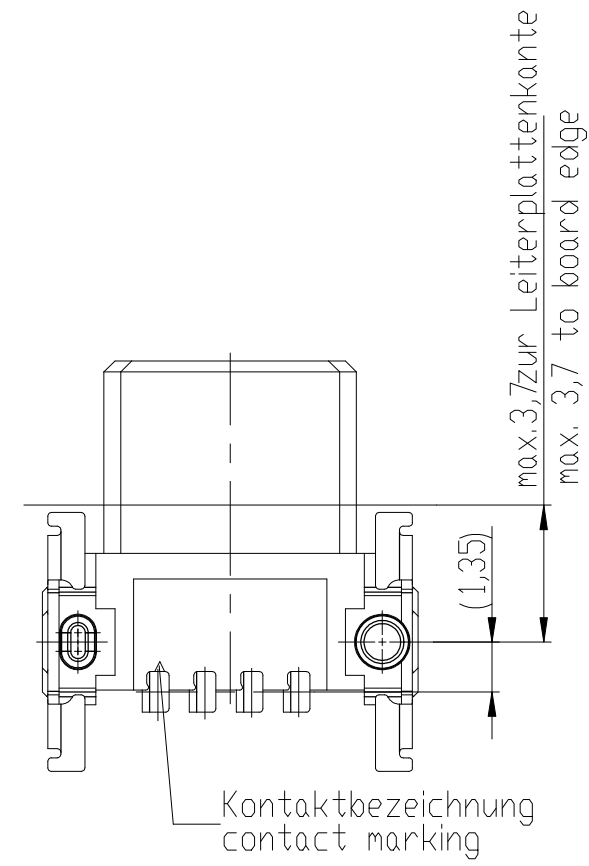
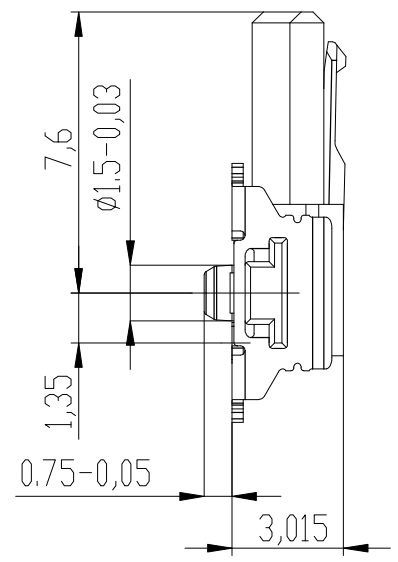
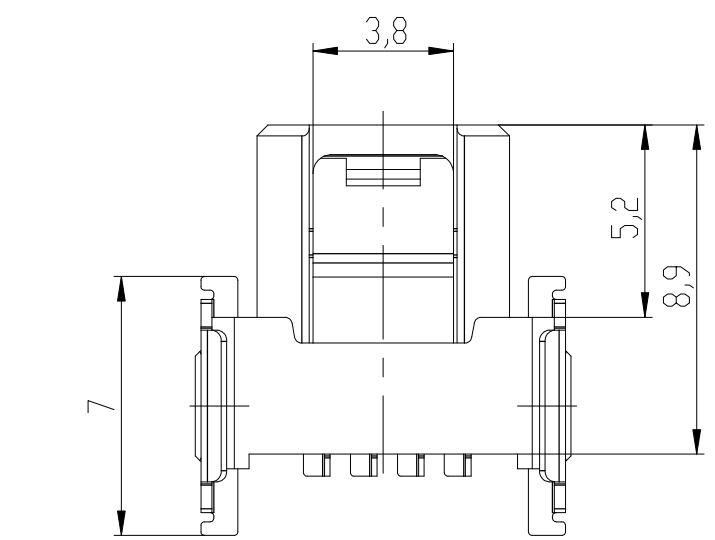
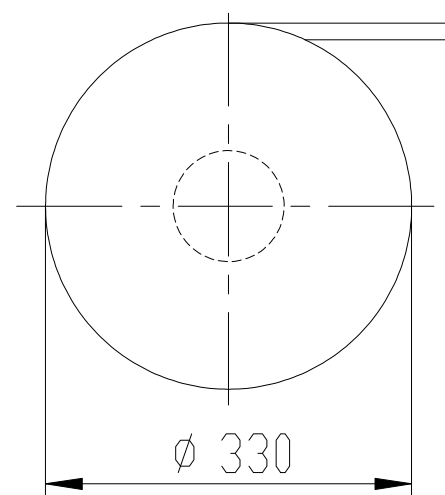
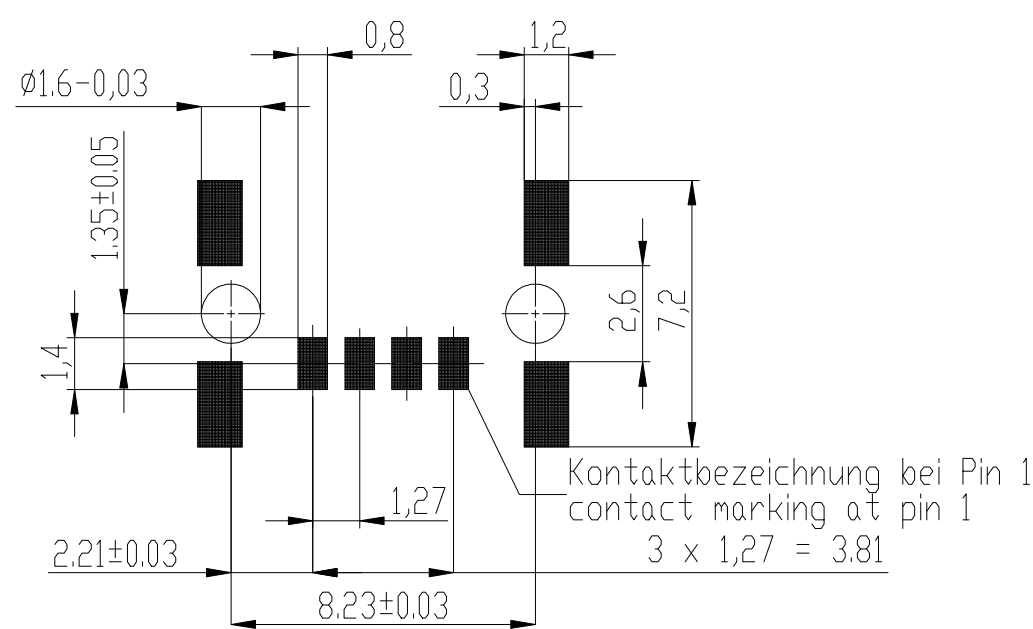


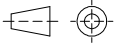
Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 850 Stück
Packaging unit: 850 pcs



Anforderungsstufe 1
Performance Level 1
Kontaktbereich vergoldet
Mating Area gold plating
Anschlussbereich verzinkt 4-6 μ m
Terminal Area 4-6 μ m tin plating
Koplanarität der Anschlüsse ≤ 0.1 mm
Coplanarity Area of Termination ≤ 0.1 mm

Copyright by TE GmbH
Proprietary notice pursuant to ISO 15006 to be observed.

Information: ohne Hilfsmittel lösbar without tool unlockable				Tolerances	 All Dimensions in mm	Scale 5:1	mit Verriegelung with locking mechanism	
<u>Customer drawing:</u> THIS DRAWING IS A CONTROLLED DOCUMENT.				Subject to modification without prior notice. Drawing will not be updated.	 TE Connectivity	Designation ERNI-F 1,27 SRC P, 4-polig BA1		
						©- 364485-E		
b		15.07.2015				I A3		
Index		Date				Class SRCP		